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TITLE: Decreasing removing rate of polishing for low dielectric constant material comprises directly integrating low dielectric constant material into copper damascene process

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PRIORITY-DATA: 1999TW-0110309 (June 21, 1999)

PATENT-FAMILY:

| PUB-NO | PUB-DATE | LANGUAGE | PAGES | MAIN-IPC |
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| TW 420844 A | February 1, 2001 | N/A | 020 | H01L 021/304 |

APPLICATION-DATA:

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| TW 420844A | N/A | 1999TW-0110309 | June 21, 1999 |

INT-CL (IPC): H01L021/304

ABSTRACTED-PUB-NO: TW 420844A

BASIC-ABSTRACT: NOVELTY - Decreasing the removing rate of polishing for low

dielectric constant material comprises depositing a low dielectric constant material on a semiconductor substrate to form a dielectric layer, and performing an NH3 plasma, N2 plasma or Ar plasma process to increase the density degree of the dielectric layer, thereby decreasing the removing rate of polishing.

ADVANTAGE - The selectivity of chemical mechanical polishing process is increased, so as to assist the integration of the low dielectric constant material and copper damascene process.

CHOSEN-DRAWING: Dwg.1/2

TITLE-TERMS:

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EV 182656495

DECREASE REMOVE RATE POLISH LOW DIELECTRIC CONSTANT
MATERIAL COMPRISE INTEGRATE
LOW DIELECTRIC CONSTANT MATERIAL COPPER PROCESS

DERWENT-CLASS: L03 U11

CPI-CODES: L04-C26;

EPI-CODES: U11-C06A1A;

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C2001-155438

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